



Welcome to [E-XFL.COM](https://www.e-xfl.com)

### Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### Applications of Embedded - CPLDs

#### Details

Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/epm7064tc44-15">https://www.e-xfl.com/product-detail/intel/epm7064tc44-15</a>

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See [Table 4](#).

<b>Table 4. MAX 7000 Device Features</b>			
<b>Feature</b>	<b>EPM7032 EPM7064 EPM7096</b>	<b>All MAX 7000E Devices</b>	<b>All MAX 7000S Devices</b>
ISP via JTAG interface			✓
JTAG BST circuitry			✓ <sup>(1)</sup>
Open-drain output option			✓
Fast input registers		✓	✓
Six global output enables		✓	✓
Two global clocks		✓	✓
Slew-rate control		✓	✓
MultiVolt interface <sup>(2)</sup>	✓	✓	✓
Programmable register	✓	✓	✓
Parallel expanders	✓	✓	✓
Shared expanders	✓	✓	✓
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	✓	✓	✓

**Notes:**

- (1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
- (2) The MultiVolt I/O interface is not available in 44-pin packages.

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2.0.0 and 3.0.0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

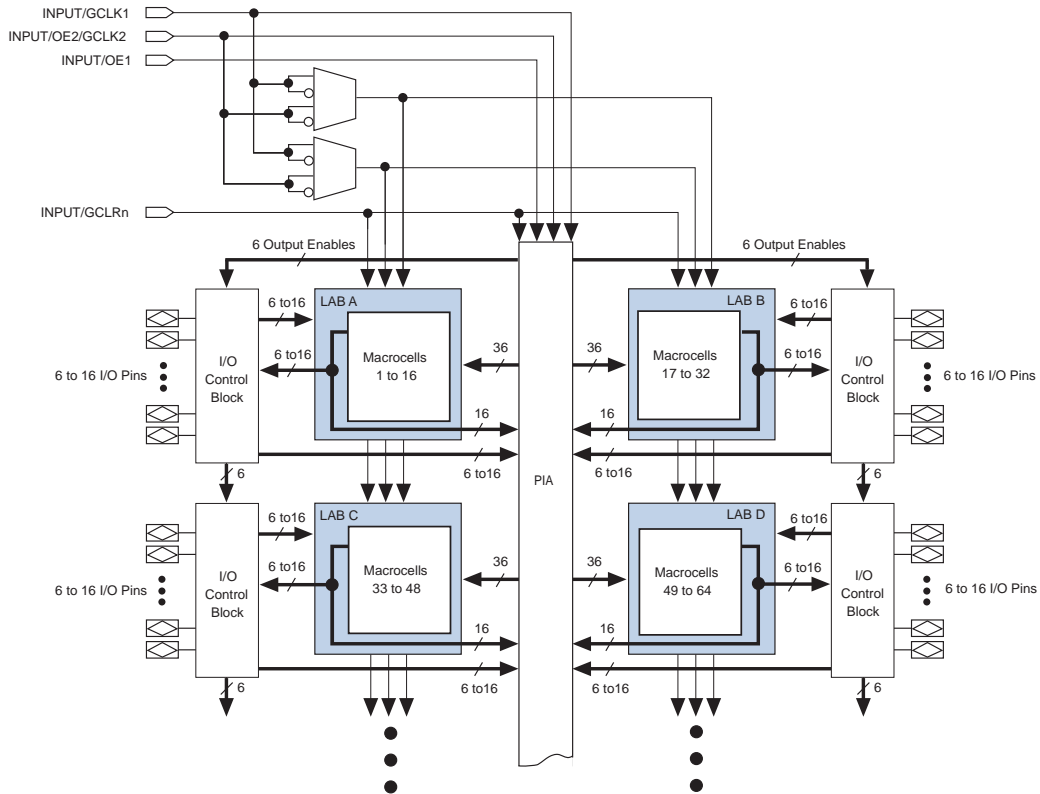
## Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

Figure 2 shows the architecture of MAX 7000E and MAX 7000S devices.

**Figure 2. MAX 7000E & MAX 7000S Device Block Diagram**



## Logic Array Blocks

The MAX 7000 device architecture is based on the linking of high-performance, flexible, logic array modules called logic array blocks (LABs). LABs consist of 16-macrocell arrays, as shown in Figures 1 and 2. Multiple LABs are linked together via the programmable interconnect array (PIA), a global bus that is fed by all dedicated inputs, I/O pins, and macrocells.

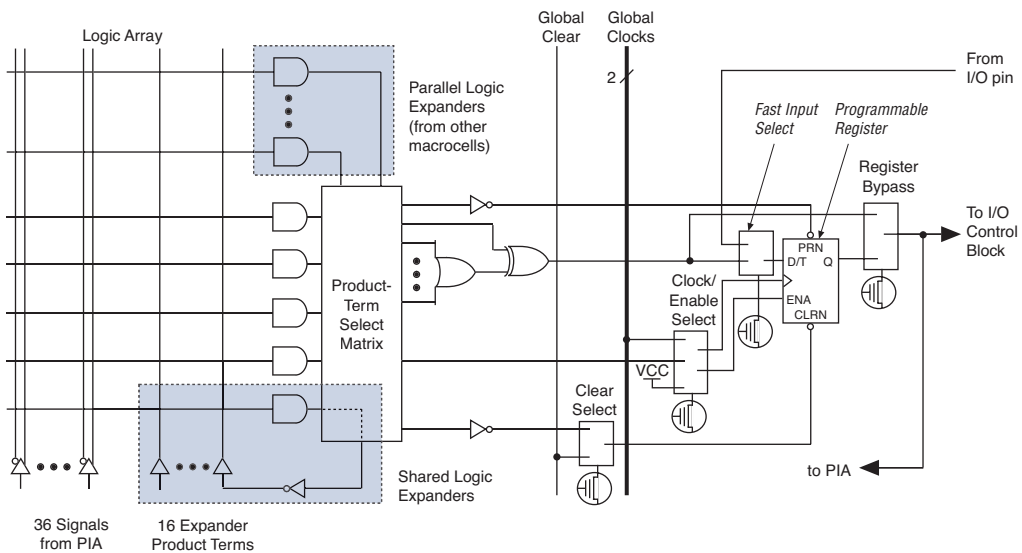
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

## Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

**Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell**

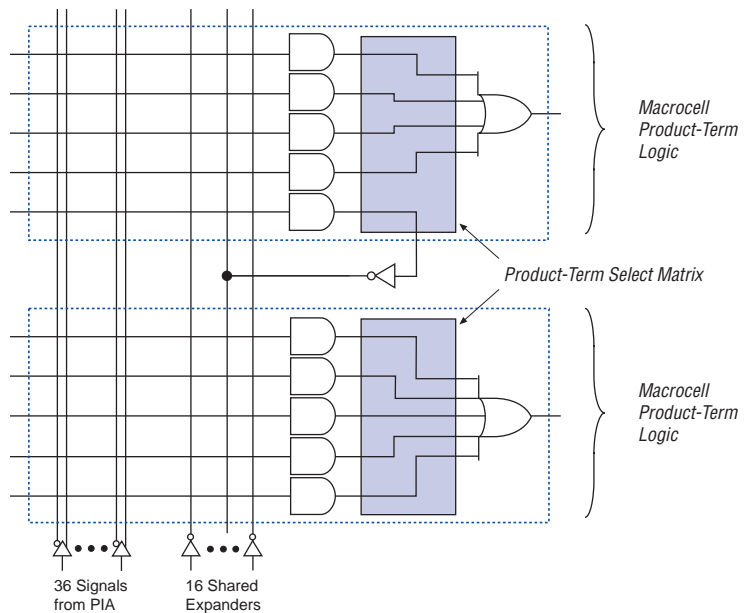


### Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay ( $t_{SEXP}$ ) is incurred when shareable expanders are used. Figure 5 shows how shareable expanders can feed multiple macrocells.

**Figure 5. Shareable Expanders**

*Shareable expanders can be shared by any or all macrocells in an LAB.*



### Parallel Expanders

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with five product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

## IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. [Table 9](#) describes the JTAG instructions supported by the MAX 7000 family. The pin-out tables (see the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information) show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

**Table 9. MAX 7000 JTAG Instructions**

JTAG Instruction	Devices	Description
SAMPLE/PRELOAD	EPM7128S EPM7160S EPM7192S EPM7256S	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	EPM7128S EPM7160S EPM7192S EPM7256S	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ISP Instructions	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	These instructions are used when programming MAX 7000S devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, BitBlaster download cable, or using a Jam File (.jam), Jam Byte-Code file (.jbc), or Serial Vector Format file (.svf) via an embedded processor or test equipment.

The instruction register length of MAX 7000S devices is 10 bits. Tables 10 and 11 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

**Table 10. MAX 7000S Boundary-Scan Register Length**

Device	Boundary-Scan Register Length
EPM7032S	1 (1)
EPM7064S	1 (1)
EPM7128S	288
EPM7160S	312
EPM7192S	360
EPM7256S	480

**Note:**

- (1) This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

**Table 11. 32-Bit MAX 7000 Device IDCODE** Note (1)

Device	IDCODE (32 Bits)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)
EPM7032S	0000	0111 0000 0011 0010	00001101110	1
EPM7064S	0000	0111 0000 0110 0100	00001101110	1
EPM7128S	0000	0111 0001 0010 1000	00001101110	1
EPM7160S	0000	0111 0001 0110 0000	00001101110	1
EPM7192S	0000	0111 0001 1001 0010	00001101110	1
EPM7256S	0000	0111 0010 0101 0110	00001101110	1

**Notes:**

- (1) The most significant bit (MSB) is on the left.  
 (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.



Figure 9 shows the timing requirements for the JTAG signals.

**Figure 9. MAX 7000 JTAG Waveforms**

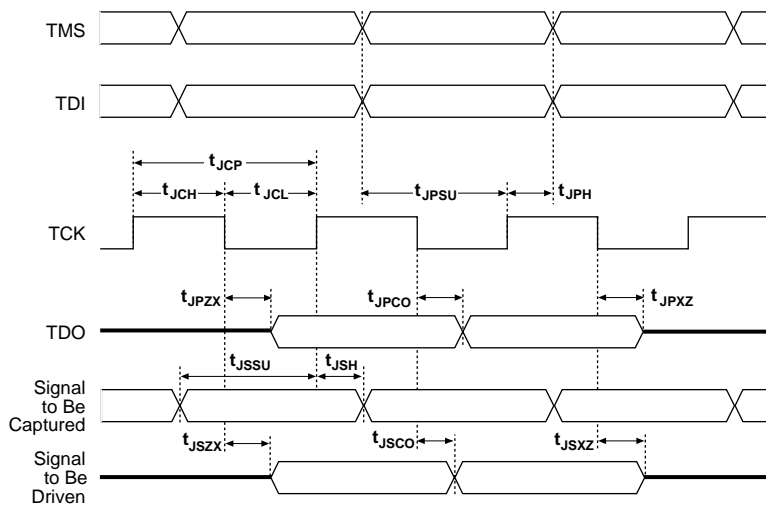


Table 12 shows the JTAG timing parameters and values for MAX 7000S devices.

Symbol	Parameter	Min	Max	Unit
$t_{JCP}$	TCK clock period	100		ns
$t_{JCH}$	TCK clock high time	50		ns
$t_{JCL}$	TCK clock low time	50		ns
$t_{JPSU}$	JTAG port setup time	20		ns
$t_{JPH}$	JTAG port hold time	45		ns
$t_{JPCO}$	JTAG port clock to output		25	ns
$t_{JPZX}$	JTAG port high impedance to valid output		25	ns
$t_{JPXZ}$	JTAG port valid output to high impedance		25	ns
$t_{JSSU}$	Capture register setup time	20		ns
$t_{JSH}$	Capture register hold time	45		ns
$t_{JSCO}$	Update register clock to output		25	ns
$t_{JSZX}$	Update register high impedance to valid output		25	ns
$t_{JSXZ}$	Update register valid output to high impedance		25	ns



For more information, see [Application Note 39 \(IEEE 1149.1 \(JTAG\) Boundary-Scan Testing in Altera Devices\)](#).

**Table 15. MAX 7000 5.0-V Device DC Operating Conditions** *Note (9)*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{IH}$	High-level input voltage		2.0	$V_{CCINT} + 0.5$	V
$V_{IL}$	Low-level input voltage		-0.5 (8)	0.8	V
$V_{OH}$	5.0-V high-level TTL output voltage	$I_{OH} = -4$ mA DC, $V_{CCIO} = 4.75$ V (10)	2.4		V
	3.3-V high-level TTL output voltage	$I_{OH} = -4$ mA DC, $V_{CCIO} = 3.00$ V (10)	2.4		V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1$ mA DC, $V_{CCIO} = 3.0$ V (10)	$V_{CCIO} - 0.2$		V
$V_{OL}$	5.0-V low-level TTL output voltage	$I_{OL} = 12$ mA DC, $V_{CCIO} = 4.75$ V (11)		0.45	V
	3.3-V low-level TTL output voltage	$I_{OL} = 12$ mA DC, $V_{CCIO} = 3.00$ V (11)		0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1$ mA DC, $V_{CCIO} = 3.0$ V (11)		0.2	V
$I_I$	Leakage current of dedicated input pins	$V_I = -0.5$ to $5.5$ V (11)	-10	10	$\mu$ A
$I_{OZ}$	I/O pin tri-state output off-state current	$V_I = -0.5$ to $5.5$ V (11), (12)	-40	40	$\mu$ A

**Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices** *Note (13)*

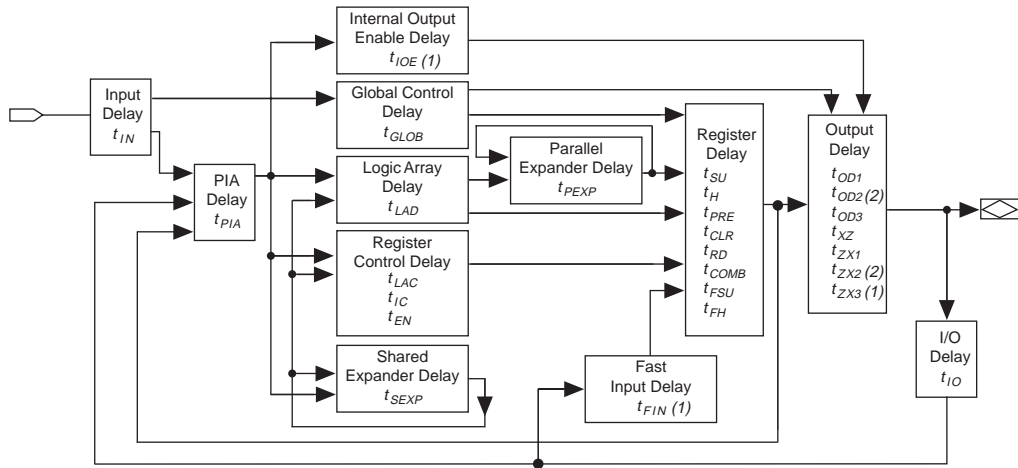
Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		12	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		12	pF

**Table 17. MAX 7000 5.0-V Device Capacitance: MAX 7000E Devices** *Note (13)*

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		15	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		15	pF

**Table 18. MAX 7000 5.0-V Device Capacitance: MAX 7000S Devices** *Note (13)*

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Dedicated input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		10	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		10	pF

**Figure 12. MAX 7000 Timing Model****Notes:**

- (1) Only available in MAX 7000E and MAX 7000S devices.
- (2) Not available in 44-pin devices.

The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 13 shows the internal timing relationship of internal and external delay parameters.



For more information, see [Application Note 94 \(Understanding MAX 7000 Timing\)](#).

### Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- (3) This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (7) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

**Table 27. EPM7032S External Timing Parameters (Part 1 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t <sub>SU</sub>	Global clock setup time		2.9		4.0		5.0		7.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t <sub>CH</sub>	Global clock high time		2.0		2.5		3.0		4.0		ns
t <sub>CL</sub>	Global clock low time		2.0		2.5		3.0		4.0		ns
t <sub>ASU</sub>	Array clock setup time		0.7		0.9		1.1		2.0		ns
t <sub>AH</sub>	Array clock hold time		1.8		2.1		2.7		3.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t <sub>ACH</sub>	Array clock high time		2.5		2.5		3.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		2.5		2.5		3.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			5.7		7.0		8.6		10.0	ns

**Table 29. EPM7064S External Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
t <sub>ACH</sub>	Array clock high time		2.5		2.5		3.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		2.5		2.5		3.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			5.7		7.1		8.0		10.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			5.7		7.1		8.0		10.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

**Table 30. EPM7064S Internal Timing Parameters (Part 1 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
$t_{FIN}$	Fast input delay			2.2		2.6		1.0		1.0	ns
$t_{SEXP}$	Shared expander delay			3.1		3.8		4.0		5.0	ns
$t_{PEXP}$	Parallel expander delay			0.9		1.1		0.8		0.8	ns
$t_{LAD}$	Logic array delay			2.6		3.2		3.0		5.0	ns
$t_{LAC}$	Logic control array delay			2.5		3.2		3.0		5.0	ns
$t_{IOE}$	Internal output enable delay			0.7		0.8		2.0		2.0	ns
$t_{OD1}$	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
$t_{OD2}$	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		2.5		2.0	ns
$t_{OD3}$	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
$t_{ZX2}$	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
$t_{ZX3}$	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
$t_{SU}$	Register setup time		0.8		1.0		3.0		2.0		ns
$t_H$	Register hold time		1.7		2.0		2.0		3.0		ns

**Table 30. EPM7064S Internal Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{FSU}$	Register setup time of fast input		1.9		1.8		3.0		3.0		ns
$t_{FH}$	Register hold time of fast input		0.6		0.7		0.5		0.5		ns
$t_{RD}$	Register delay			1.2		1.6		1.0		2.0	ns
$t_{COMB}$	Combinatorial delay			0.9		1.0		1.0		2.0	ns
$t_{IC}$	Array clock delay			2.7		3.3		3.0		5.0	ns
$t_{EN}$	Register enable time			2.6		3.2		3.0		5.0	ns
$t_{GLOB}$	Global control delay			1.6		1.9		1.0		1.0	ns
$t_{PRE}$	Register preset time			2.0		2.4		2.0		3.0	ns
$t_{CLR}$	Register clear time			2.0		2.4		2.0		3.0	ns
$t_{PIA}$	PIA delay	(7)		1.1		1.3		1.0		1.0	ns
$t_{LPA}$	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns

**Notes to tables:**

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3\text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$  and  $t_{CPW}$  parameters for macrocells running in the low-power mode.

**Table 36. EPM7192S Internal Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
$t_H$	Register hold time		1.7		3.0		4.0		ns
$t_{FSU}$	Register setup time of fast input		2.3		3.0		2.0		ns
$t_{FH}$	Register hold time of fast input		0.7		0.5		1.0		ns
$t_{RD}$	Register delay			1.4		2.0		1.0	ns
$t_{COMB}$	Combinatorial delay			1.2		2.0		1.0	ns
$t_{IC}$	Array clock delay			3.2		5.0		6.0	ns
$t_{EN}$	Register enable time			3.1		5.0		6.0	ns
$t_{GLOB}$	Global control delay			2.5		1.0		1.0	ns
$t_{PRE}$	Register preset time			2.7		3.0		4.0	ns
$t_{CLR}$	Register clear time			2.7		3.0		4.0	ns
$t_{PIA}$	PIA delay	(7)		2.4		1.0		2.0	ns
$t_{LPA}$	Low-power adder	(8)		10.0		11.0		13.0	ns

**Notes to tables:**

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3\text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$  and  $t_{CPW}$  parameters for macrocells running in the low-power mode.

Tables 37 and 38 show the EPM7256S AC operating conditions.

**Table 37. EPM7256S External Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t <sub>SU</sub>	Global clock setup time		3.9		7.0		11.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.5		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t <sub>CH</sub>	Global clock high time		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time		0.8		2.0		4.0		ns
t <sub>AH</sub>	Array clock hold time		1.9		3.0		4.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns
t <sub>ACH</sub>	Array clock high time		3.0		4.0		6.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		4.0		6.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			7.8		10.0		13.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	128.2		100.0		76.9		MHz
t <sub>ACNT</sub>	Minimum array clock period			7.8		10.0		13.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	128.2		100.0		76.9		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz



**Table 38. EPM7256S Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.3		0.5		2.0	ns
$t_{IO}$	I/O input pad and buffer delay			0.3		0.5		2.0	ns
$t_{FIN}$	Fast input delay			3.4		1.0		2.0	ns
$t_{SEXP}$	Shared expander delay			3.9		5.0		8.0	ns
$t_{PEXP}$	Parallel expander delay			1.1		0.8		1.0	ns
$t_{LAD}$	Logic array delay			2.6		5.0		6.0	ns
$t_{LAC}$	Logic control array delay			2.6		5.0		6.0	ns
$t_{IOE}$	Internal output enable delay			0.8		2.0		3.0	ns
$t_{OD1}$	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
$t_{OD2}$	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
$t_{OD3}$	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
$t_{ZX2}$	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
$t_{ZX3}$	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
$t_{SU}$	Register setup time		1.1		2.0		4.0		ns
$t_H$	Register hold time		1.6		3.0		4.0		ns
$t_{FSU}$	Register setup time of fast input		2.4		3.0		2.0		ns
$t_{FH}$	Register hold time of fast input		0.6		0.5		1.0		ns
$t_{RD}$	Register delay			1.1		2.0		1.0	ns
$t_{COMB}$	Combinatorial delay			1.1		2.0		1.0	ns
$t_{IC}$	Array clock delay			2.9		5.0		6.0	ns
$t_{EN}$	Register enable time			2.6		5.0		6.0	ns
$t_{GLOB}$	Global control delay			2.8		1.0		1.0	ns
$t_{PRE}$	Register preset time			2.7		3.0		4.0	ns
$t_{CLR}$	Register clear time			2.7		3.0		4.0	ns
$t_{PIA}$	PIA delay	(7)		3.0		1.0		2.0	ns
$t_{LPA}$	Low-power adder	(8)		10.0		11.0		13.0	ns

**Notes to tables:**

- (1) These values are specified under the recommended operating conditions shown in [Table 14](#). See [Figure 13](#) for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3\text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPTW}$  parameters for macrocells running in the low-power mode.

## Power Consumption

Supply power (P) versus frequency ( $f_{MAX}$  in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The  $P_{IO}$  value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in [Application Note 74 \(Evaluating Power for Altera Devices\)](#).

The  $I_{CCINT}$  value, which depends on the switching frequency and the application logic, is calculated with the following equation:

$$I_{CCINT} =$$

$$A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times \text{tog}_{LC}$$

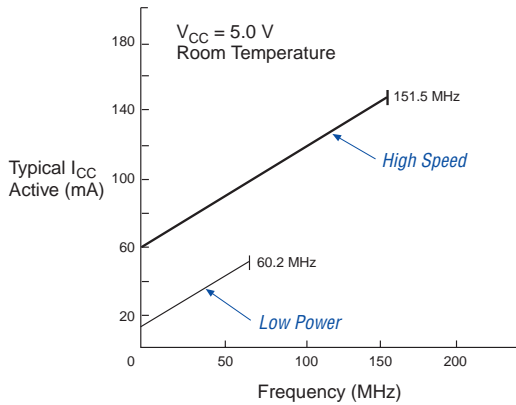
The parameters in this equation are shown below:

$MC_{TON}$	=	Number of macrocells with the Turbo Bit option turned on, as reported in the MAX+PLUS II Report File ( <b>.rpt</b> )
$MC_{DEV}$	=	Number of macrocells in the device
$MC_{USED}$	=	Total number of macrocells in the design, as reported in the MAX+PLUS II Report File ( <b>.rpt</b> )
$f_{MAX}$	=	Highest clock frequency to the device
$\text{tog}_{LC}$	=	Average ratio of logic cells toggling at each clock (typically 0.125)
A, B, C	=	Constants, shown in <a href="#">Table 39</a>

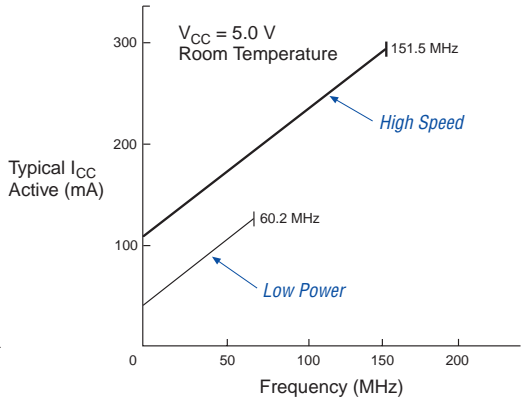
Figure 14 shows typical supply current versus frequency for MAX 7000 devices.

Figure 14.  $I_{CC}$  vs. Frequency for MAX 7000 Devices (Part 1 of 2)

EPM7032



EPM7064



EPM7096

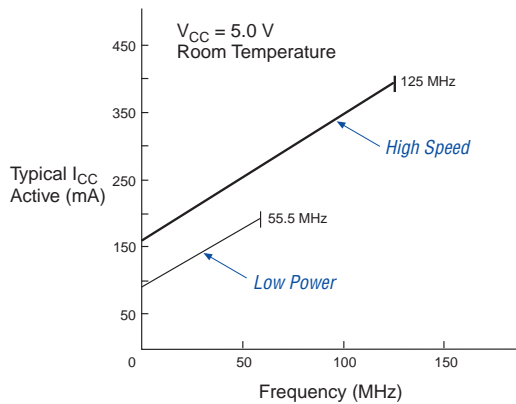
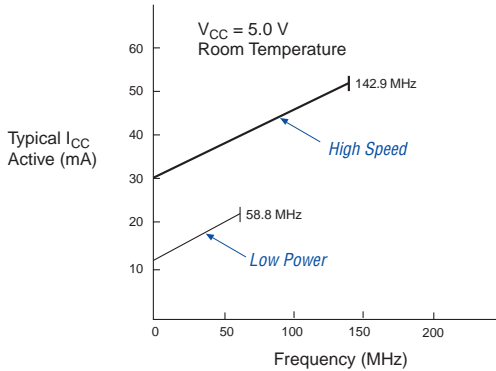


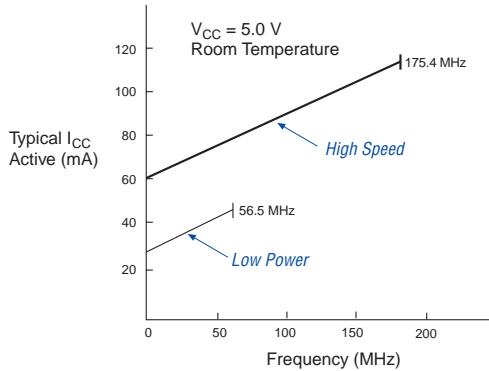
Figure 15 shows typical supply current versus frequency for MAX 7000S devices.

**Figure 15.  $I_{CC}$  vs. Frequency for MAX 7000S Devices (Part 1 of 2)**

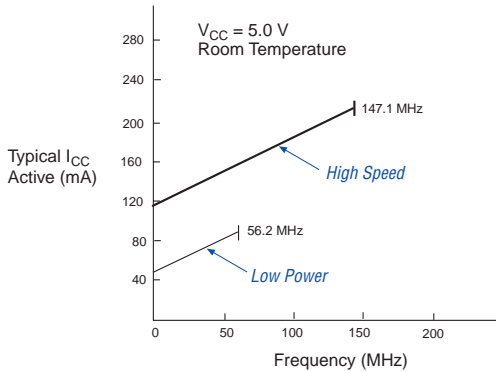
**EPM7032S**



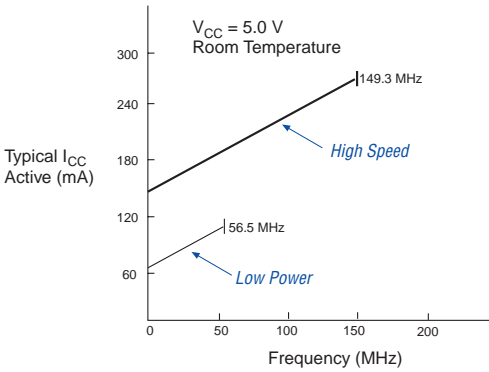
**EPM7064S**

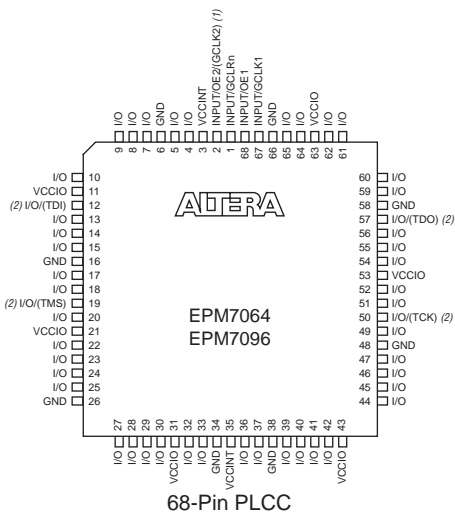


**EPM7128S**



**EPM7160S**



**Figure 17. 68-Pin Package Pin-Out Diagram***Package outlines not drawn to scale.***Notes:**

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.